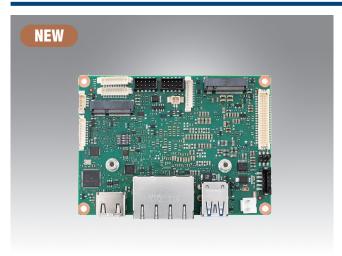


Intel® Atom® x6000 Series Processor (Code Name: Elkhart Lake) **Pico-ITX SBC**



Features

- Intel Atom x6000E Series
- Onboard LPDDR4x up to 8GB and EMMC up to 128GB
- Support 12~24V wide voltage range and -40~85°C operating temperature
- 2x GbE LAN, 2x USB3.2, 2x RS-232/422/485, I2C
- M.2 E-Key and B-Key for SATA storage, option to support RS-232 module
- Support iManager & Software APIs, WISE-DeviceOn, and EdgeAl Suite

Software APIs:



















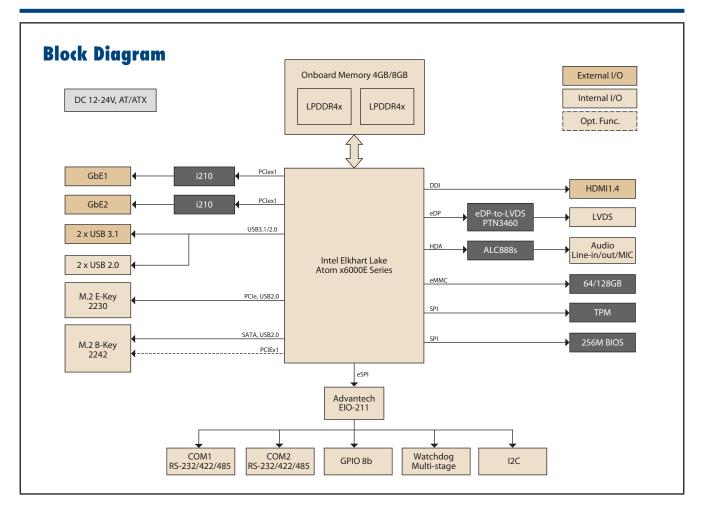




Specifications

Processor MC11 MC12 MC					
Max. Frequency 3.00Hz 3.00Hz 3.00Hz 4.00Hz 4.		Processor	x6211E	x6413E	x6425E
Pilettom					
Petition			1.3GHz		2.0GHz
Patients	Platform				
Polity					
Discost Disc					
Memory			***	300	1211
Memory M					
Max. Capacity 468 468 468 468 468				I DDDD4v 2200	I DDDD 4v, 2722
Memory Clamer Content BECC					
BECC BECC BECC BECC BECC BECC BECC	Memory			4GB	868
Singe	•			IDEAA	IDEAA
Controller Intel® LIP Graphics for 10th Gen Intel® Processors	2.				
Graphies Max. Frequency 750MHz 750MHz 500MHz	Storage				128GB
Standard Standard					
Sase Frequency SOUNTY SO	Granhice				
LCD	шаршь	Base Frequency	350MHz	500MHz	500MHz
BDM		3D/HW Acceleration	DX12, OGL4.5, OCL1.2, Vulkan 1.1; HV	V encode HEVC/H.265, MPEG2, JPEG/MJPEG	
Multiple Display		LCD	LVDS Dual Channel 18/24-bit LVDS		
Ethernet	Display I/F	HDMI	Up to 2160 x 3840 @ 30Hz		
Ethernet		Multiple Display			
Speed 10/100/1000 Mtps	F., .	Controller	2 x RJ-45,LAN1: Intel i210, LAN2: Intel	i210	
External I/O VGA/HDM/DP	Ethernet	Speed	10/100/1000 Mbps		
External I/O VGA-HDM/OP -1/I- VGA-HDM/OP					
External I/O					
Power DC-Jack	External I/O				
SATA					
USB2.0 2 Serial Bus 1x FC COM Port 2x RS-232/422/485 COM Port 2x RS-232/42/485 COM Port 2x RS-232/422/485 COM Port 2x RS-232/422/48					
Serial Bus					
COM Port 2 x RS-23/42/485					
Internal I/O GPIO 8-bit general purpose input output I/O Audio Realtek ALC888, Line-in/Line-out/MIC Investor 12V/5V LPC/SPI Bus eSPI for EIO-211 / SPI for TPM / no LPC Front Panel Control Power-on, Reset, Buzzer, SATA LED, CaseOpen Board Feature TPM Programmable 1 - 6553 sec/mi Expansion M.2 1 XM.2 E-Key for 2230 module (PCIsat, USB 2.0 to support SATA storage, BOM option to PClext to support PCle storage or RS-232 module) Expansion M.2 1 XM.2 E-Key for 2242 module (SATA, USB2.0 to support SATA storage, BOM option to PClext to support PCle storage or RS-232 module) Expansion M.2 1 XM.2 E-Key for 2242 module (SATA, USB2.0 to support SATA storage, BOM option to PClext to support PCle storage or RS-232 module) Evance Supply Voltage Vin: DC 12-24V +/- 10%, RTC Battery: Lithium 3V/210mAH Vin: DC 12-24V +/- 10%, RTC Battery: Lithium 3V/210mAH Connector 2pin Power Connector (1800); Optional: DC-IN Jack Vin: DC 12-24V +/- 10%, RTC Battery: Lithium 3V/210mAH Vin: DC 12-24V +/- 10%, RTC Battery: Lithium 3V/210mAH Vin: DC 12-24V +/- 10%, RTC Battery: Lithium 3V/210mAH Vin: DC 12-24V +/- 10%, RTC Battery: Lithium 3V/210mAH Vin: DC 12-24V +/- 10%, RTC Battery: Lithium 3V/210mAH Vin: DC 12-24V +/- 10%, RTC Battery: Lithium 3V/210mAH <t< td=""><td></td><td></td><td></td><td></td><td></td></t<>					
Audio Realtek ALC888, Line-in/Line-out/MIC Invertor 12V/5V EV/5V E	1.1				
Invertor	internal I/O				
LPC/SPI Bus eSPI for EI0-211 / SPI for TPM / no LPC					
Front Panel Control Power-on, Reset, Buzzer, SATA LED, CaseOpen					
Watchdog Timer					
TPM				seOpen	
IManager 3.0 SW API for Hardware Monitor, Smart Fan Control, Brightness Control, I2C, GPIO, WDT					
Tx M.2 E-Key for 2230 module (PClex1, USB 2.0 to support wireless module) 1x M.2 E-Key for 2242 module (PClex1, USB 2.0 to support wireless module) 1x M.2 E-Key for 2242 module (PClex1, USB 2.0 to support wireless module) 1x M.2 E-Key for 2242 module (PClex1, USB 2.0 to support wireless module) 1x M.2 E-Key for 2242 module (PClex1, USB 2.0 to support wireless module) 2x M.2 E-Key for 2242 module (PClex1, USB 2.0 to support vireless module) 2x M.2 E-Key for 2242 module (PClex1, USB 2.0 to support vireless module) 2x M.2 E-Key for 2242 module (PClex1, USB 2.0 to support vireless module) 2x M.2 E-Key for 2242 module (PClex1, USB 2.0 to support vireless module) 2x M.2 E-Key for 2242 module (PClex1, USB 2.0 to support vireless module) 2x M.2 E-Key for 2242 module (PClex1, USB 2.0 to support vireless module) 2x M.2 E-Key for 2242 module (PClex1, USB 2.0 to support SATA storage; BOM option to PClex1 to support PCle storage; BOM option to PClex1 to Support PClex1 to Suppo	Board Feature				
Supply Voltage Vir. DC 12-24V +/- 10%; RTC Battery. Lithium 3V/210mAH		iManager 3.0			
Supply Voltage Vin: DC 12-24V +/- 10%, RTC Battery: Lithium 3V/210mAH	Evnansion	M 2			
Connector 2pin Power Connector (180D); Optional: DC-IN Jack	Елранотоп				Clex1 to support PCle storage or RS-232 module)
Power Management AT, ATX		Supply Voltage	Vin: DC 12~24V +/- 10%; RTC Battery:	Lithium 3V/210mAH	
Max. Consumption 22.30W (12V), 23.86W (24V) 27.40W (12V), 29.65W (24V) 27.86W (12V), 29.81W (24V) Idle Consumption 9.26W (12V), 11.21W (24V) 9.41W (12V), 11.90W (24V) 8.95W (12V), 11.37W (24V) Temperature Operating Standard: 0 - 60 °C (32 ~ 140 °F) with 0.7m/s airflow Storage: 40 - 85 °C (-40 ~ 185 °F) with 0.7m/s airflow Storage: 60 °C @ 95% relative humidity, non-condensing Storage: 60 °C @ 95% relative humidity, non-condensing Vibration Resistance 3.5 Grms Certification EMC CE, FCC Class B Mechanical Dimensions 100 x 72 mm (3.9" x 2.8")			2pin Power Connector (180D); Optiona	I: DC-IN Jack	
Idle Consumption 9.26W (12V), 11.21W (24V) 9.41W (12V), 11.90W (24V) 8.95W (12V), 11.37W (24V)	Power	Power Management	AT, ATX		
Idle Consumption 9.26W (12V), 11.21W (24V) 9.41W (12V), 11.90W (24V) 8.95W (12V), 11.37W (24V)		Max. Consumption	22.30W (12V), 23.86W (24V)	27.40W (12V), 29.65W (24V)	27.86W (12V), 29.81W (24V)
Temperature Operating Standard: 0 ~ 60 °C (32 ~ 140 °F) with 0.7m/s airflow Operating Extend: ~40 ~ 85 °C (~40 ~ 185 °F) Humidity Operating: 40 °C @ 95% relative humidity, non-condensing Storage: 60 °C @ 95% relative humidity, non-condensing Vibration Resistance 3.5 Grms Certification EMC CE, FCC Class B Mechanical Dimensions 100 x 72 mm (3.9" x 2.8")		·		. , , , , , ,	. , , , , ,
Humidity Operating: 40 °C @ 95% relative humidity, non-condensing Storage: 60 °C @ 95% relative humidity, non-condensing Vibration Resistance 3.5 Grms Certification EMC CE, FCC Class B Mechanical Dimensions 100 x 72 mm (3.9" x 2.8")			Operating Standard: 0 ~ 60 °C (32 ~ 14 Operating Extend: -40 ~ 85 °C (-40 ~ 1	10 °F) with 0.7m/s airflow	
Certification EMC CE, FCC Class B Mechanical Dimensions 100 x 72 mm (3.9" x 2.8")	Environment	*	Operating: 40 °C @ 95% relative humion Storage: 60 °C @ 95% relative humidity		
Mechanical Dimensions 100 x 72 mm (3.9" x 2.8")					
Mechanical	Certification	EMC	CE, FCC Class B		
Wecutating Net Weight 86g	Machanical	Dimensions	100 x 72 mm (3.9" x 2.8")		
	iviecnaffical	Net Weight	86g		

*Note: xxxx



Ordering Information

PN	CPU	Max. Frequency	Core	Memory	eMMC	USB3.2	GbE	Cable Kit	Thermal Solution	Operating Temperature
MIO-2363AW-P1A1	x6211E	3.0GHz	2	4GB	64GB	2	2	Υ	Y; Passive	-40 ~ 85 °C
MIO-2363AW-P2A1	x6413E	3.0GHz	4	4GB	64GB	2	2	Υ	Y; Passive	-40 ~ 85 °C
MIO-2363AW-P3A1	x6425E	3.0GHz	4	8GB	128GB	2	2	Υ	Y; Passive	-40 ~ 85 °C
MIO-2363ALW-P1A1	x6211E	3.0GHz	2	4GB	64GB	2	2	N	N	-40 ~ 85 °C
MIO-2363ALW-P3A1	x6425E	3.0GHz	4	8GB	128GB	2	2	N	N	-40 ~ 85 °C

Packing List

Part No.	Description	Quantity
	MIO-2363 SBC	1
2006236300	Startup Manual	1
1970005240T001	MIO-2363 Passive Heatsink	1
1700030406-01	USB cable (2 ports, 20cm)	1
1700030404-01	COM port cable (20cm)	2
1700019584-01	Audio cable (3 phone jacks, 20cm)	1
1700019705-01	ATX 2x2P power cable (10cm)	1

Rear I/O View



Optional Accessories

Part No.	Description
1970005500N001	MIO-2363 heatspreader

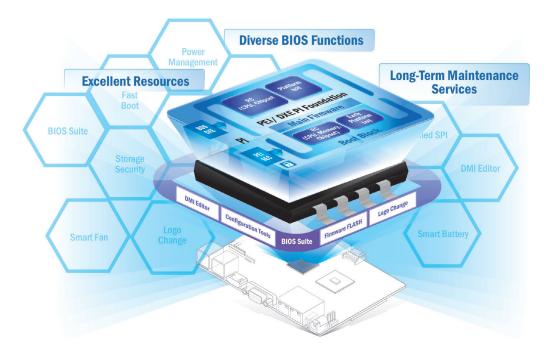
Embedded OS/API

OS	Part No.	Description
Win10	20706WX1ES0123	64-bit (UEFI mode only)
Ubuntu	20706U20DS0026	Ubuntu Desktop 20.04 LTS 64-bit Image & License Sticker for MIO-2363
Yocto BSP	Support by Request	Yocto BSP and Test Image
Software API	Website Download	SUSI v4.0

Reliable Embedded BIOS Solutions

Custom BIOS services with long-term support

Advantech's high-quality embedded BIOS solutions deliver rapid execution and feature expert BIOS team support. These solutions feature multi-functional designs that ensure security and enable power/boot management. Advantech further provides 10+ years of BIOS version management, internal management, and longevity support for both hardware and BIOS — enhancing application efficiency, diversifying functionality, and optimizing performance.



Embedded BIOS Solution Advantages

Sufficient Sources

- Strong partnership with BIOS vendors
- 50+ engineers with extensive industrial BIOS experience

Diverse BIOS Functions

- Multi-layer security
- 3 second fast boot
- Power management
- BIOS suite utility

Long-Term Maintenance Services

- · Platform longevity support
- 10-year BIOS version control
- BIOS remote backup

Value-Added Customization Process



Embedded Linux Support and Design-in Services

Hardware Certified Ubuntu and Yocto with Eco Partner Services

Linux is the most popular embedded OS for transportation, outdoor services, factory automation, and mission critical applications. Its open source and kernel reliability features ease security updates, and make it particularly adaptable to new AI and Edge computing technology. Advantech has cooperated with Canonical and other software partners to provide hardware certified Ubuntu image and Yocto BSP as Linux offerings. The Advantech, Embedded Linux, and Android Alliance (ELAA) delivers local software services and



Features

Certified OS and BSP

- · Platform compatibility tests
- Preloaded functional driver and software stacks

Licensed Services

- · License authorized Canonical delivers 10-years of bug fixes and security updates
- In-house bundled service

Numerous Al and Edge Resources

- Containerized technology for service provision and deployment
- · Al resources from Caffe. TensorFlow, and mxnet

Local Partner Alliance

Embedded Linux and Android Alliance (ELAA)

Edge Al Suite

Al development for diverse application at the Edge

Increasing demand for AI inference/analytic capabilities at the Edge make AI training models, software development environments, and hardware configuration key factors in successful solution deployment. Advantech's Edge AI Suite helps users build AI demo devices quickly and choose optimal hardware solutions easily.



5x Performance Boost

- Integrated Intel[®]
 OpenVINO™
 technology
- Boost Al using Advantech hardware

All-in-one Installation

- Build AI
 environment in
 under 5 minutes
- Ready-to-use configuration

One Click Al Experience

- User friendly configuration guidance
- One-click
 Benchmark
 acquisition

Plug-and-play Environment

- Easy access to 100+ Al inference extensions
- Software development package available

Discover Cost-effective Hardware

- Diverse CPU/RAM options
- Find hardware solutions for Al development

WISE-DeviceOn

Massive IoT Device Management Utility

IoT deployment and management typically involves numerous disparate devices installed on multiple sites. These devices require effective monitoring, managing, and tracking. Advantech's easy-to-use WISE-DeviceOn interface enables users to remotely monitor device health, troubleshoot problems, and send software/firmware updates over-the-air (OTA). In sum, DeviceOn empowers quick real-time responsiveness to emerging problems.



Features

Comprehensive Management

- · Devices status
- · Peripherals/firmware
- · Open for extension

Remote Access

- · Real-time monitoring
- · Remote controls
- Troubleshooting

Efficient Operations

- · Zero-touch on-boarding
- OTA updates
- · Batch control

Product Highlights



SOM-6883

High-performance 11th Gen Intel[®] COMe Type 6 Module



MIO-5375

Compact 11th Gen Intel[®] Outdoor Focused 3.5" SBC



EPC-B5587

10th Gen Intel[®] Xeon[®] based Edge server



EPC-R3220 Arm based IoT Edge Gateway